

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

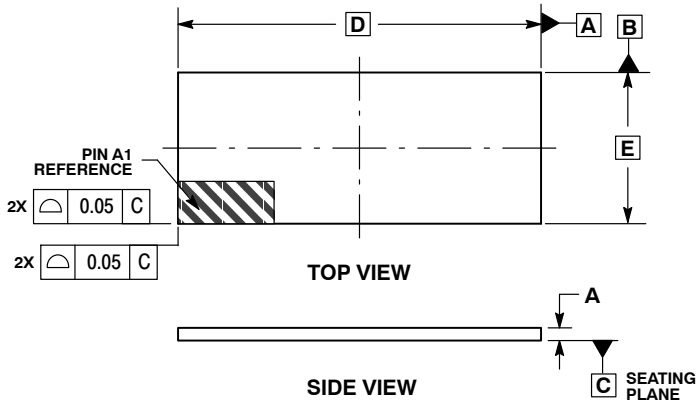
ON Semiconductor®



WLCSP8, 6.00x2.50 / EFCP6025-8EGJ-021  
CASE 567MC  
ISSUE O

SCALE 2:1

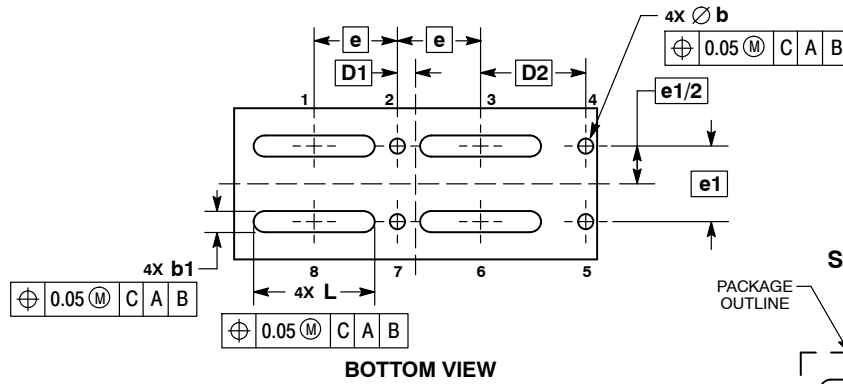
DATE 22 JUL 2015



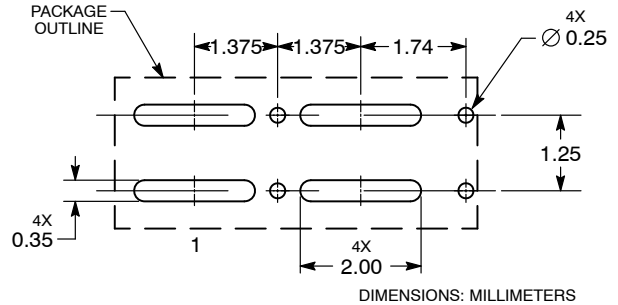
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.19	0.23
b	0.22	0.28
b1	0.32	0.38
D	5.95	6.05
D1	0.305 BSC	
D2	1.740 BSC	
E	2.45	2.55
e	1.375 BSC	
e1	1.25 BSC	
L	1.97	2.03



**RECOMMENDED SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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